

METHOD AND SYSTEM FOR ASSEMBLING A PRINTED CIRCUIT  
BOARD USING A LAND GRID ARRAY

ABSTRACT OF THE DISCLOSURE

A device for assembling circuit boards. The device has an upper  
5 surface for receiving a compressing force. The device also has a lower  
surface for compressing a number of compression devices in a land grid  
array assembly while allowing access to a number of fasteners associated  
with the compression devices. The device is able to assist in the formation  
of an electrical contact between a chip package in the land grid array  
10 assembly and a circuit board by the lower surface being pressed against  
the compression devices to compress the compression devices and then  
allowing the plurality of fasteners to be tightened.

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